Lecture 1: VLSI Overview CSCE 6933/5933 Advanced Topics in VLSI Systems

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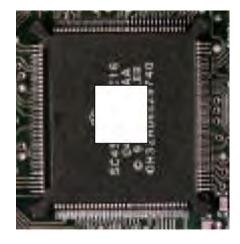
What is an Integrated Circuit ?

- An integrated circuits is a silicon semiconductor crystal containing the electronic components for digital gates.
- Integrated Circuit is abbreviated as IC.
- The digital gates are interconnected to implement a Boolean function in a IC .
- The crystal is mounted in a ceramic/plastic material and external connections called "pins" are made available.
- ICs are informally called chips.





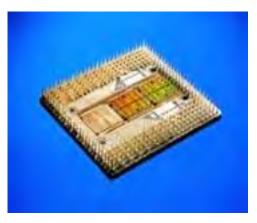
How does a chip look like?



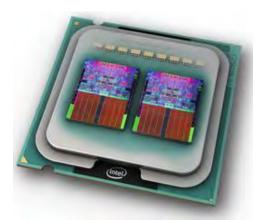
(1) ASIC



(2) Sun UltraSparc



(3) PentiumPro



Core 2 Quad: (2006)





Different Attributes of an IC or chip

- Transistor count of a chip
- Operating frequency of a chip
- Power consumption of a chip
- Power density in a chip
- Size of a device used in chip

NOTE: Chip is informal name for IC.







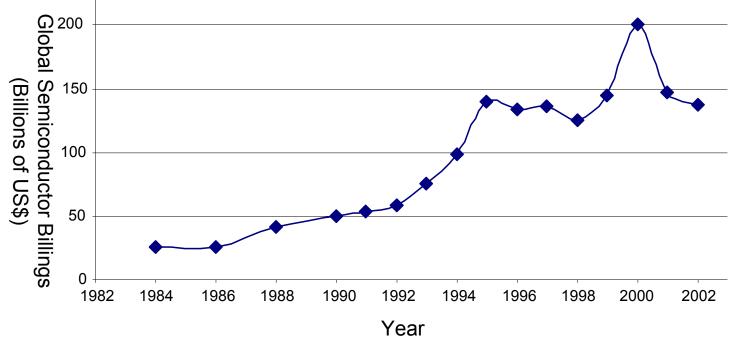
VLSI Technology: Highest Growth in History

- 1958: First integrated circuit
 - Flip-flop using two transistors
 - Built by Jack Kilby at Texas Instruments
- 2003
 - Intel Pentium 4 μ processor (55 million transistors)
 - 512 Mbit DRAM (> 0.5 billion transistors)
- 53% compound annual growth rate over 45 years
 - No other technology has grown so fast so long
- Driven by miniaturization of transistors
 - Smaller is cheaper, faster, lower in power!
 - Revolutionary effects on society



VLSI Industry : Annual Sales

- 10¹⁸ transistors manufactured in 2003
 100 million for every human on the planet
- 340 Billion transistors manufactured in 2006. (World population 6.5 Billion!)







Invention of the Transistor

- Invention of transistor is the driving factor of growth of the VLSI technology
- Vacuum tubes ruled in first half of 20th century Large, expensive, power-hungry, unreliable
- 1947: first point contact transistor
 - John Bardeen and Walter Brattain at Bell Labs
 - Earned Nobel prize in 1956







Transistor Types

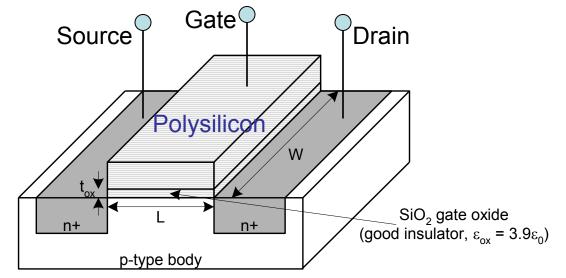
- Bipolar transistors
 - n-p-n or p-n-p silicon structure
 - Small current into very thin base layer controls large currents between emitter and collector
 - Base currents limit integration density
- Metal Oxide Semiconductor Field Effect Transistors (MOSFET)
 - nMOS and pMOS MOSFETS
 - Voltage applied to insulated gate controls current between source and drain
 - Low power allows very high integration





Conventional MOS Transistor: Poly Gate

- Four terminals: gate, source, drain, body (bulk, or substrate)
- Gate oxide body stack looks like a capacitor
 - Gate and body are conductors
 - SiO₂ (oxide) is a very good insulator
 - Called metal oxide semiconductor (MOS) capacitor
 - Even though gate is no longer made of metal

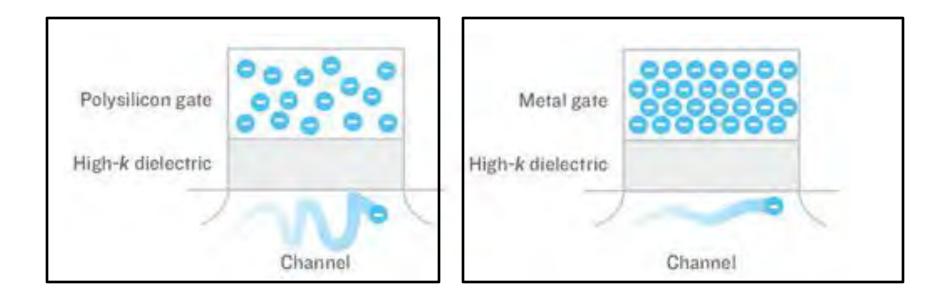


Refer for use of poly: Vasdaz, L.L., Grove, A. S., Rowe, T. A., Moore, G. E. "Silicon Gate Technology," *IEEE Spectrum*, Vol. 6 No. 10 (October 1969) pp. 28-35.





MOS Devices: High- κ

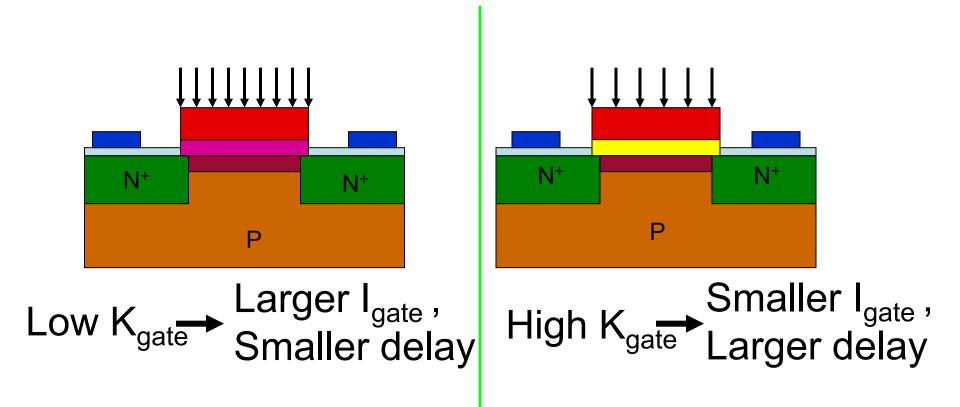


Source: IEEE Spectrum October 2007.





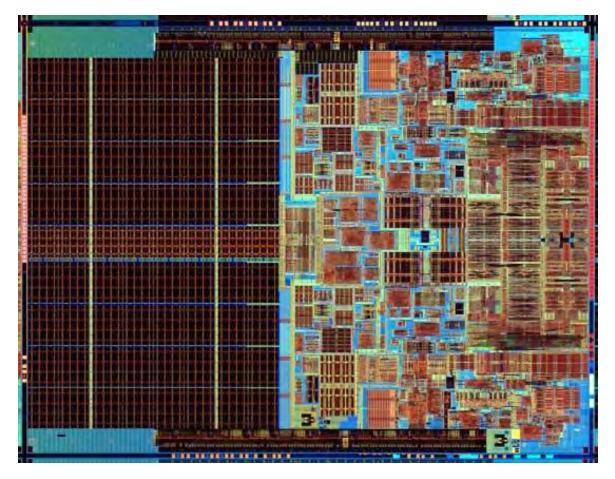
MOS Devices: Classical Vs Nonclassical







Core 2 Duo: 291M Transistors (2006)



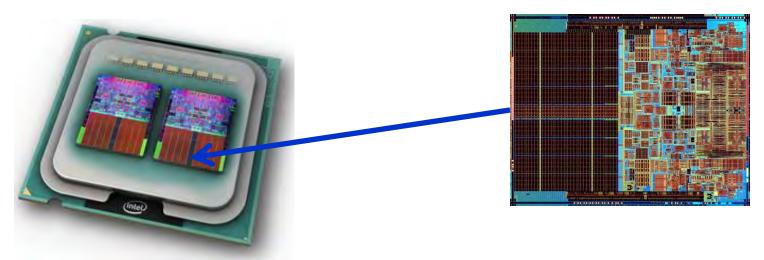
Core 2 Duo T5000/T7000 series mobile processors, called Penryn uses 800M of 45 nanometer devices (2007).





VLSI Trend : CPU

- Core 2 Duo has 291M transistors (2006).
- Core 2 Duo T5000/T7000 series mobile processors, called Penryn uses 800M of 45 nanometer devices (2007).



Core 2 Quad: (2006)

Source: http://www.gearfuse.com/





VLSI Trend: 32nm



Source: Ryan Shrout, PC Perspective,

http://www.pcper.com/





VLSI Trend: 32nm

Tick-Tock Development Model: Sustained Microprocessor Leadership



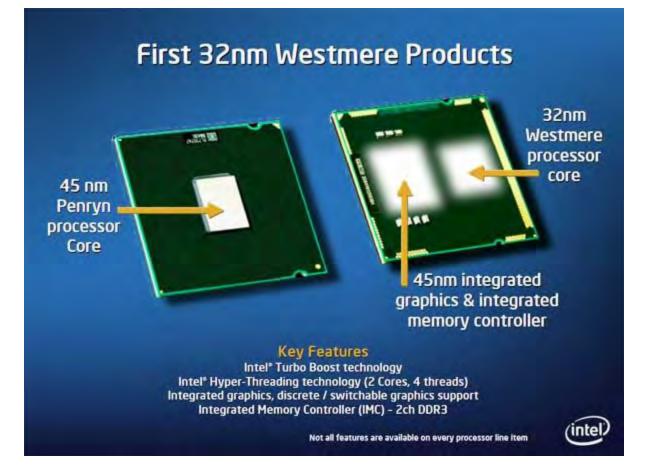
Source: Ryan Shrout, PC Perspective,

http://www.pcper.com/





VLSI Trend: 32nm



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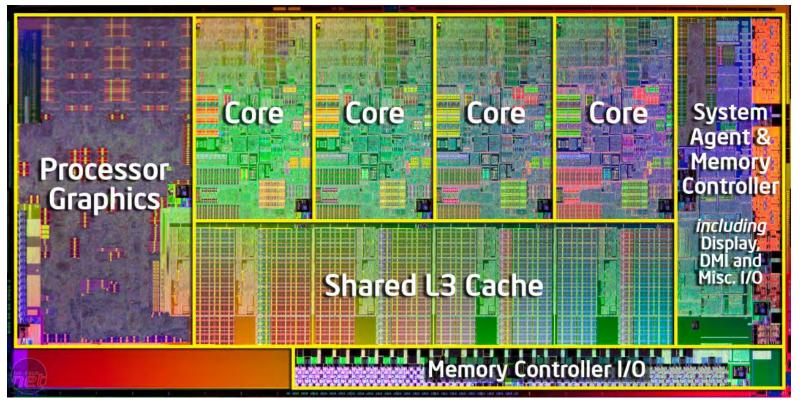
http://www.pcper.com/







Intel Sandy Bridge -- 2011



Source: http://www.bit-tech.net

- Quad core i.e. 4 cores per die; 8 threads.
- 4 Cores + Graphics Cores + Memory Controller.
- 8 MB of cache.
- 1 billion transistors on the die. 32nm CMOS technology.





Intel Sandy Bridge – Facts ...

- There are 1 billion transistors. If a car were to have 1 billion parts, it would take a car manufacturer 114 years to assemble this car.
- If the processor were a country and its transistor count was a country's population, it would be the third most populated country.
- The processor contains 540 million more transistors than the number of registered cars in the European Union, the USA and the Asia Pacific region combined.
- If the power consumption of a laptop based on this processor is compared with an electric clothes dryer, drying one load for 60 minutes is equivalent to running a laptop for 147 hours or 6 days and 2.4 hours.

Source: http://www.techspot.com



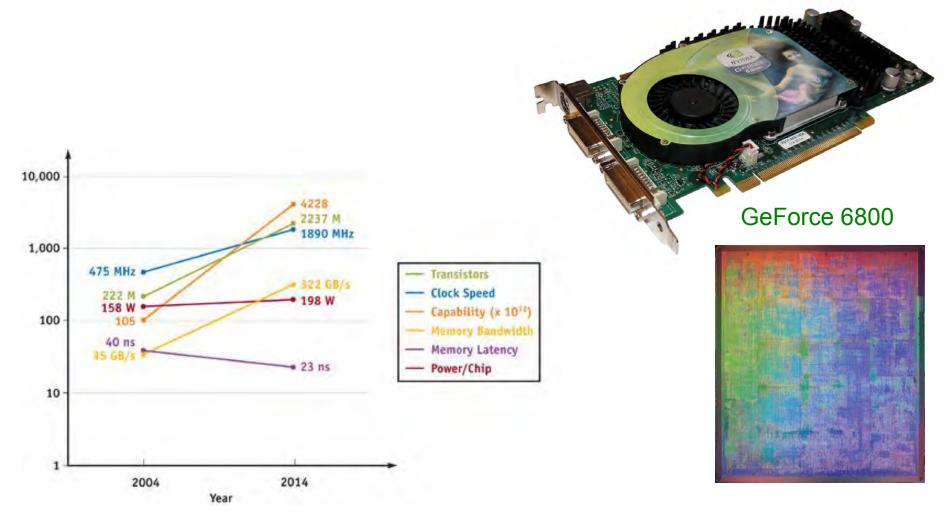
Intel Sandy Bridge – Facts

- If the processor is compared with an electric oven, baking a pizza for 45 minutes at 350 degrees (Fahrenheit) is equivalent to running 67 laptops for 50 hours.
- If every home in the United States had 30 light switches it would take the new chips about 1 nanosecond to turn on all 3.57 billion light switches.
- Compared to Intel's first microprocessor, the 4004, a 32nm CPU runs over 4,000 times as fast and each transistor uses about 4,000 times less energy. The price per transistor has dropped by a factor of about 100,000.
- This processor is printed on very pure silicon, which is refined from common beach sand. So the sand you once stepped on at a beache may be powering your notebook.

Source: http://www.techspot.com



VLSI Trend : GPU



Source: GPU Gems 2





VLSI Trend : Salient Points

Increased Complexity: 340 Billion transistors manufactured in 2006.

(World population 6.5 Billion!)

- **High Power Dissipation**: Power dissipation per transistor has reduced, but power dissipation of overall chip increasing.
- Increased Parallelism with Multicore Architecture: To archive highest performance multiples have been put together in the same die.
- Smaller Process Technology: Use of smaller nanoscale CMOS technology, 32nm node and high- κ CMOS.
- Reduced Time-to-market: For competitiveness and profit.





Why Technology Scaling?

- Technology shrinks by 0.7/generation
- With every generation can integrate 2x more functions per chip; chip cost does not increase significantly
- Cost of a function decreases by 2x
- However ...

Discover the power of ideas

- How to design chips with more and more functions?
- Design engineering population does not double every two years...
- Hence, a need for more efficient design methods
 - Exploit different levels of abstraction



Integrated Circuits Categories

There are many different types of ICs as listed below.

IC Categories	Functions	
Analog ICs	Amplifiers	
	Filters	
Digital ICs	Boolean Gates	
	Encoders/Decoders	
	Multiplexers / Demultiplexers	
	Flip-flops	
	Counters	
	Shift Registers	
Hybrid ICs	Mixed Signal Processors	
Interface ICs	Analog-Digital Converters	
	Digital-Analog Converters	





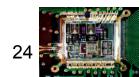


Levels of Integration (Chip Complexity)

Categorized by the number of gates contained in the chip.

IC Complexity	Number of Gates	Functional Complexity	Examples
SSI	<10	Basic gates	Inverters, AND gates, OR gates, NAND gates, NOR gates
MSI	10-100	Basic gates	Exclusive OR/NOR
		Sub-modules	Adders, subtractors, encoders, decoders, multiplexers, demultiplexers, counters, flip-flops
LSI	100-1000s	Functional modules	Shift registers, stacks
VLSI	1000s- 100,000	Major building blocks	Microprocessors, memories
ULSI	>100,000	Complete systems	Single chip computers, digital signal processors
WSI	>10,000,000	Distributed systems	Microprocessor systems





Digital Logic Families

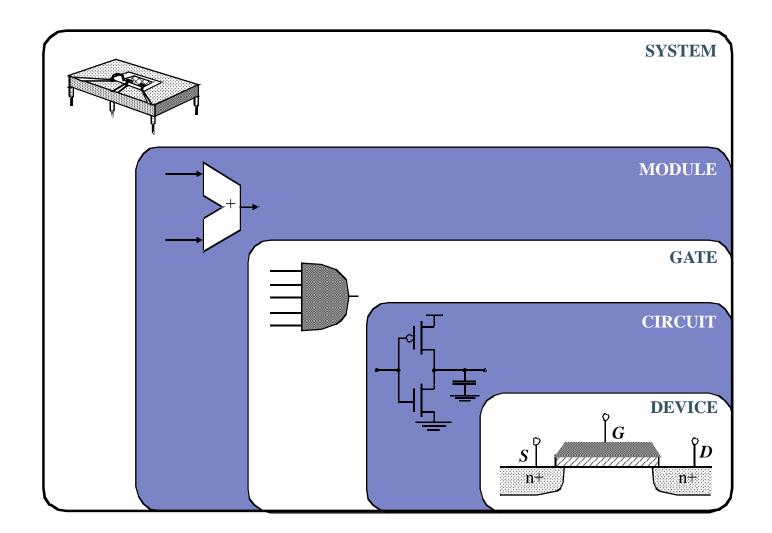
- Various circuit technology used to implement an IC at lower level of abstraction.
- The circuit technology is referred to as a digital logic family.

RTL - Resistor-transistor Logic	obsolete
DTL - Diode-transistor logic	obsolete
TTL - Transistor-transistor logic	not much used
ECL - Emitter-coupled logic	high-speed ICs
MOS - Metal-oxide semiconductor	high-component density
CMOS - Complementary Metal-oxide semiconductor	widely used, low-power high- performance and high-packing density IC
BiCMOS - Bipolar Complementary Metal-oxide semiconductor	high current and high-speed
GaAs - Gallium-Arsenide	very high speed circuits





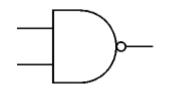
Design Abstraction Levels

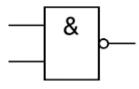






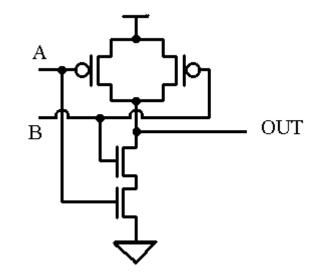
Digital Circuits : Logic to Device





(NAND Gate)

(IEC Symbol)

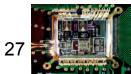


(Transistor Diagram)

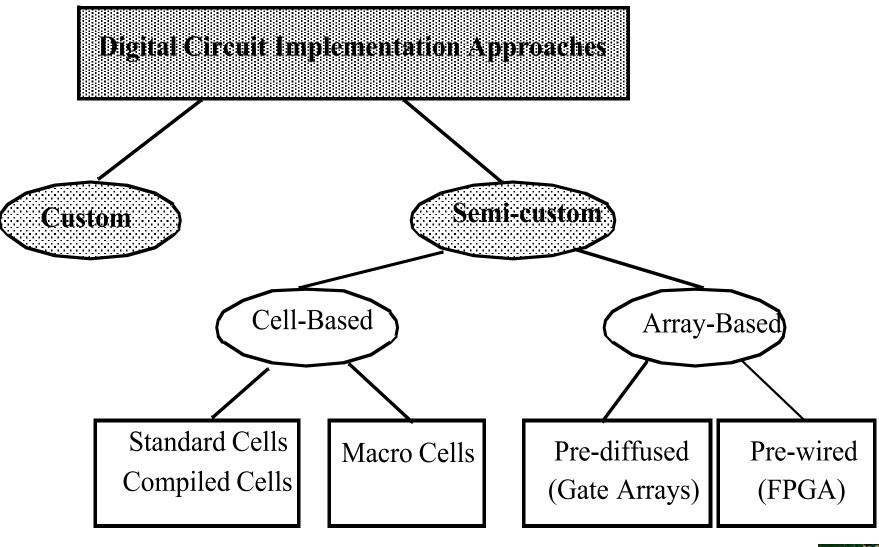




(Layout Diagram)



Implementation Approaches for Digital ICs

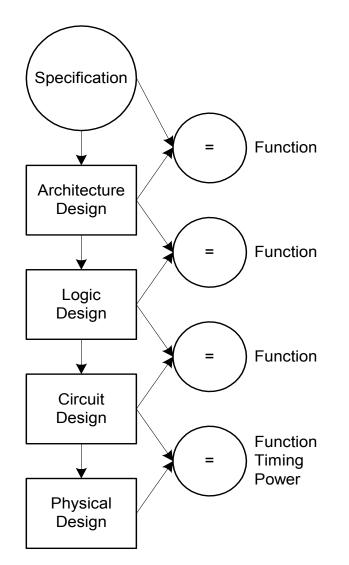




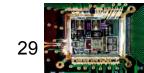
Advanced Topics in VLSI Systems



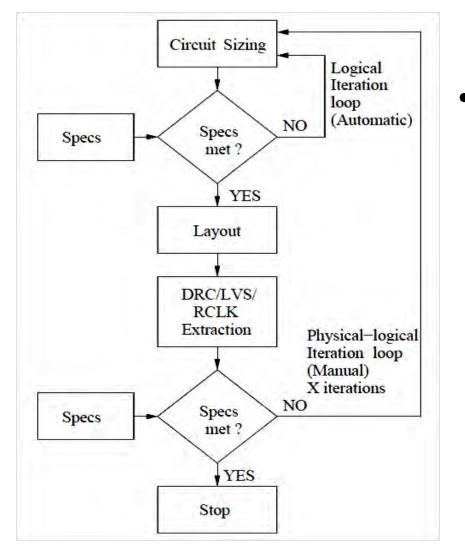
Digital Design Abstractions







Standard Custom IC Design Flow

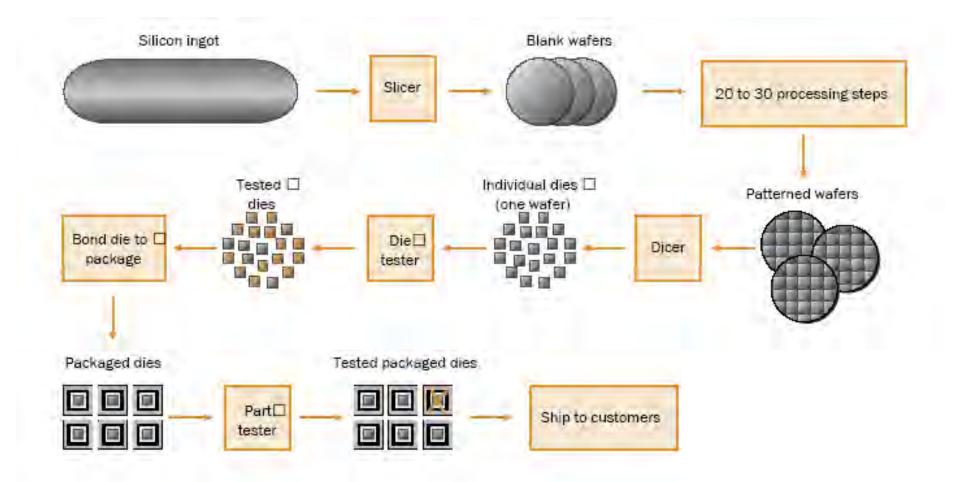


• Standard RFIC design flow requires multiple (X) manual iterations on the back-end layout to achieve parasitic closure between front-end circuit and backend layout.





Digital IC Fabrication Flow







25 Historic Chips ...

- 1. Signetics NE555 Timer (1971) : IC that functions as a timer or an oscillator which is used in everywhere from kitchen appliances, to toys, to spacecraft.
- 2. Texas Instruments TMC0281 Speech Synthesizer (1978) : The first single-chip speech synthesizer.
- 3. MOS Technology 6502 Microprocessor (1975) : An 8-bit microprocessor developed by MOS Technology for Apple I.
- 4. Texas Instruments TMS32010 Digital Signal Processor (1983) : Fastest DSP.
- 5. Microchip Technology PIC 16C84 Microcontroller (1993) : Used EEPROM (electrically erasable programmable read-only memory) for easy changing of code, which is used in everywhere as an industrial controllers.
- 6. Fairchild Semiconductor µA741 Op-Amp (1968) : Used in audio and video preamplifiers, voltage comparators, precision rectifiers, etc.
- 7. Intersil ICL8038 Waveform Generator (circa 1983) : Generates sine, square etc.
- 8. Western Digital WD1402A UART (1971) : Parallel from/to serial conversion.
- 9. Acorn Computers ARM1 Processor (1985) : 32-bit RISC processor.
- 10. Kodak KAF-1300 Image Sensor (1986) : 1.3 megapixels CCD sensor (Kodak camera was \$13,000).

Source: IEEE Spectrum May 2009.



25 Historic Chips ...

- 11. IBM Deep Blue 2 Chess Chip (1997) : 480 chess-chips each containing 1.5M transistors, won the chess match.
- 12. Transmeta Corp. Crusoe Processor (2000) : Software translated x86 instructions on the fly into Crusoe's machine code to save time and power.
- 13. Texas Instruments Digital Micromirror Device (1987) : Digital light-processing (DLP) used in theaters, rear-projection TVs, and projectors.
- 14. Intel 8088 Microprocessor (1979) : The 16-bit CPU used in IBM PCs.
- 15. Micronas Semiconductor MAS3507 MP3 Decoder (1997) : A RISC-based DSP with an instruction set optimized for audio compression and decompression.
- 16. Mostek MK4096 4-Kilobit DRAM (1973) : Used address multiplexing so that DRAM wouldn't require more pins as memory density increased.
- 17. Xilinx XC2064 FPGA (1985) : Field-programmable chip.
- 18. Zilog Z80 Microprocessor (1976) : A simple single-chip cheap microcontroller.
- 19. Sun Microsystems SPARC Processor (1987) : A 32-bit RISC processor called SPARC (for Scalable Processor Architecture).
- 20. Tripath Technology TA2020 AudioAmplifier (1998) : A solid-state amplifier produced high-quality sound.

Source: IEEE Spectrum May 2009.

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25 Historic Chips

21. Amati Communications Overture ADSL Chip Set (1994) : DSL chip set.

- 22. Motorola MC68000 Microprocessor (1979) : Hybrid 16-bit/32-bit microprocessor.
- 23. Chips & Technologies AT Chip Set (1985) : C&T developed 5 chips that performed the functionality of the AT motherboard that used ~100 chips.
- 24. Computer Cowboys Sh-Boom Processor (1988) : Sh-Boom was operated faster than the clock on the circuit board that drove the rest of the computer while still staying synchronized with the rest of the computer. This is of course the typical scenario!
- 25. Toshiba NAND Flash Memory (1989) : The flash chip based on NAND technology is present in every gadget, such as cell phones, digital cameras, music players, and USB drives.



Source: IEEE Spectrum May 2009.

